

Workshop On Integrated Power Packaging Invites Paper Submissions

[IWIPP 2021](#), a PSMA and IEEE sponsored workshop, will be held April 28 to 30, 2021, on the beautiful campus of Aalborg University, in Aalborg, Denmark. IWIPP is a growing and successful power technology workshop with excellent speakers and networking opportunities.

Under the leadership of general chairman Francesco Iannuzzo, professor, Aalborg University, the International Workshop on Integrated Power Packaging (IWIPP) brings together industry, academic and government researchers in the field of power electronics components, electrical insulating materials, and packaging technologies to facilitate and promote the development and commercialization of high-density and high-efficiency power converters.

Invited presentations and contributed papers will address a range of topics, including power module design, magnetic and dielectric materials technology, component performance, and application-level impacts of packaging technology. Presenters will address important challenges and present solutions to increase reliability and manufacturability while targeting improved performance with reduced size and system cost.

Next year's program includes an exciting set of power technology and packaging keynote addresses which include:

- "Packaging, Integration and Fast switching: what has been achieved and what's next?" by Eckart Hoene, chief expert Power Electronics, Fraunhofer IZM, Germany. Only close interaction between packaging end circuit engineers will bring power electronics to the next step. This presentation will give an overview on achievements in packaging and its implementation into commercial products as well as new concepts intended to reduce the technological market barrier.
- "Environmental Trends and Challenges on Power Packaging" by Garron Morris and Chris Genthe, senior principal engineer, Rockwell Automation, USA. This keynote covers the challenges of increasing power densities, coupled with new environmental stresses stemming from changing customer locations, behaviors, and applications.
- "Electrical Topology of a Pure EV: The Porsche Taycan" by Thomas Krauss, leader of Hardware Quality, Porsche AG, Germany. This presentation gives a vivid overview on grid topology, components, construction and packaging in an EV and the issues of its implementation.
- "Paving the Way to Automotive GaN: The Importance of Packaging" by Tamara Baksht, CEO, VisIC Technologies Ltd, Israel. This presentation will discuss the arrival of the D3GaN era with the novel Depletion-mode Direct Drive GaN technology emerging as an eminently suitable technology meeting the demand of highly reliable and extremely robust product needed in critical drive applications of the electric vehicle market.
- "Insulation Materials and Systems for Power Electronic Modules: Challenges and Future Research Needs" by Mona Ghassemi, assistant professor, Virginia Tech, USA. This presentation critically reviews recent research on electrical insulation materials and systems used in power electronics devices and focuses on electrical treeing in silicone gel, PD modelling, and mitigation methods. In particular, it shows that the investigations carried out to date are in their infancy regarding the working conditions targeted for next-generation WBG power devices.



The International Workshop on Integrated Power Packaging is sponsored by the Power Sources Manufacturers Association (PSMA), the IEEE Power Electronics Society (PELS), the IEEE Electronic Packaging Society (EPS), the IEEE Dielectrics and Electrical Insulation Society (DEIS) and the European Center for Power Electronics (ECPE).

Packaging and related technologies are the key to creating high-density power sources. Attendance at this important workshop can keep you and your colleagues on the cutting edge. If you have technology advancements or research accomplishments to present to the community, technical chairman Nick Baker, assistant professor, Aalborg University, invites you to submit a digest for review by the technical committee.

The call for papers is available at <http://iwipp.org/conference/call-for-papers/>. The submission portal of the website <http://iwipp.org/conference/abstract-submission-page/> is now open and accepting submissions. Additional information regarding the workshop can be found at the conference website: <https://iwipp.org/>.

Travel Restrictions Due To COVID-19

IEEE, PSMA and the IWIPP 2021 organizing committee are carefully monitoring the developing COVID-19 outbreak. The IWIPP 2021 leadership is committed to supporting conference participants who may be unable to travel to Aalborg, Denmark from affected regions. If an attendee has an accepted paper but does not wish to travel because of COVID concerns, or has concerns with obtaining a VISA, the committee will provide opportunities for remote participation, presentation of her/his paper, and networking.